#### **Applicant Information**

Applicant Authority Type::

Inventor

Applicant One Given Name::

Ai-Sen

Family Name::

Liu

Country::

Taiwan, R.O.C.

## **Correspondence Information**

Correspondence Customer Number::27683

### **Application Information**

Title Line One::

METHOD FOR FORMING DIELECTRIC BARRIER

Title Line Two::

LAYER IN DAMASCENE STRUCTURE

**Total Drawing Sheets:** 

7

Formal Drawings?::

No

Application Type::

Utility

**Docket Number::** 

24061.142

Secrecy Order in Parent Appl?::

No

# **Representative Information**

Registration Number::

42,044

#### Assignee Information

Assignee Name::

Taiwan Semiconductor Manufacturing Company, Ltd.

Street of mailing address::

No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park

City::

Hsin-Chu

Country of mailing address::

Taiwan, R.O.C.

Postal or Zip Code::

300-77